

**AMENDMENTS TO THE SPECIFICATION:**

Please amend the paragraph beginning at line 17 on page 2 as follows:

-- Fig. 3 is a top view of the ESD safe wireless type of component according to the present invention. A dissipative layer is applied on this ESD safe wireless type of component, but the bonding pad area is not covered by the dissipative layer. The bonding pad area may be located, for example, within areas indicated by A and/or B.--.